

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Kun Li et al.
Serial No.: 10/523,777
Filed: August 28, 2003
Art Unit: 2825
Confirmation No.: 5732
Examiner: Steven R. Garland
Title: **METHOD AND SYSTEM FOR DYNAMIC MODELING AND
RECIPE OPTIMIZATION OF SEMICONDUCTOR ETCH
PROCESSES**
Our Ref: VOY-007US

Cincinnati, Ohio 45202

November 14, 2006

VIA ELECTRONIC TRANSMISSION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SUBMISSION OF REPLACEMENT DRAWINGS

Sir:

Applicants submit herewith three (3) sheets of replacement drawings depicting Figs. 1, 2, and 3. Please substitute these replacement drawings for the drawings originally filed with the above-identified application.

Applicants believe there is no fee due in connection with submission of the replacement drawings. In the event that a fee is due at this time, please charge Deposit Account No. 23-3000.

Respectfully submitted,

WOOD, HERRON & EVANS, L.L.P.

/Joseph R. Jordan/

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